ALPHA® OM-362

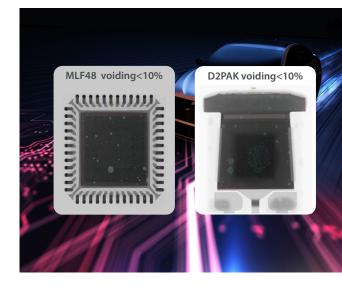
Ultra-Low Voiding, High-Reliability Solder Paste

ALPHA OM-362 is a lead-free, zero-halogen, no-clean solder paste available in T4 powder. It is designed to provide ultra-low voiding performance on all component types including bottom terminated components.

ALPHA OM-362 achieves IPC Class III voiding on BGA components averaging less than 10% voiding on Bottom Terminated Components (BTC). This paste is designed for ultralow voiding performance with high reliability alloys such as Innolot as well as traditional SAC alloys.

KEY ATTRIBUTES

- Ultra-Low Voiding Performance: Enables increased process stability, and enhances thermal and electrical performance of the most demanding component applications.
- Excellent Electromigration Characteristics: Passes J-STD-004C IPC-TM-650 at 200µm to ensure electrical reliability & functionality of fine-pitched components.
- Wide Reflow Profile Window: Enables high quality solderability of complicated, high density PCB assemblies using straight ramp and soak profiles, as high as 150° to 200°C soak.
- Good Coalescence and Wetting Performance: Coalesces down to 180µm exhibiting good wetting characteristics and solder joint reliability.
- Excellent Solder Joint and Flux Residue Cosmetics: Easily penetrable and clear flux residue enables good probe contact during quality inspection.
- Zero-Halogen, No Halogens Intentionally Added: Ensures ROHS compliance for a safe and environmentally friendly assembly process.









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